ON Semiconductor

INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION #16790D

Generic Copy

Issue Date: 18-Jan-2012

TITLE: Initial PCN for transfer from the wafer fabs Gunma and Gifu in Japan to the waferfab United Microelectronics Corporation Japan (UMCJ).

PROPOSED FIRST SHIP DATE: starting 31 May 2012 until 30 September 2012 (the actual ship date will be different by each product, please check the responsible Sales person).

AFFECTED CHANGE CATEGORY(S): Wafer Fabrication Location Change

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office.

NOTIFICATION TYPE:
Initial Product/Process Change Notification (IPCN)

First change notification sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change.

DESCRIPTION AND PURPOSE:
This is an Initial Process Change Notification to announce the transfer of products from Sanyo wafer fabrication sites located in Gunma and Gifu Japan to the waferfab United Microelectronics Corporation Japan (UMCJ).

The product design and electrical specifications will remain identical. A full electrical characterization over the temperature range will be performed for each product to check the device functionality and electrical specifications. Qualification tests are designed to show that the reliability of transferred devices will continue to meet or exceed ON Semiconductor standards.

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QUALIFICATION PLAN:

Estimated Date for Qualification Completion: starting April 2012 till September 2012, dependent of the process/product.

Samples should be available after completion of Qualification.

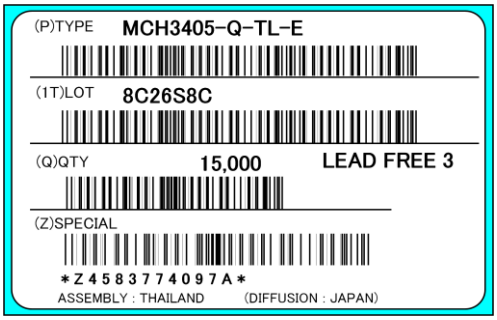
Reliability Test Plan

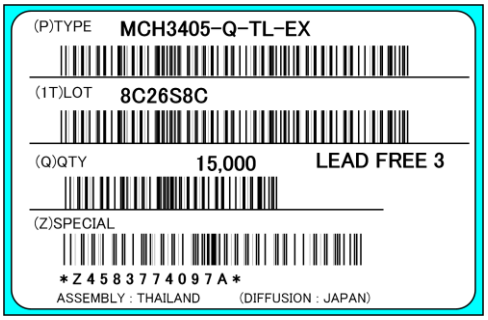
Test Items	Test Condition	Test Time	
High Temperature Storage	Tstg max	1000	h
Temperature Humidity Storage	Ta=85°C,RH=85%	1000	h
Steady State Operating Life	Tch,Tjmax	1000	h
High Temperature Revers Bias	Tstg rmax,(VDSSmax,VCESmax,VRmax)	1000	h
Temperature Cycle	Ta=Tstg min to max,30min each	200	Cycle
Pressure Cooker (Autoclave)	Ta=121degC,RH=100%,2.03×10^5Pa	50	h
Soldering Test	260degC,10s(Soldering bath)	1	time

Notice)

Part Number Identification during transfer

During transfer, we will have mixed products from new fabs and old fabs, so we need to identify which products are from new fabs or old fabs. As a means of the identification, we will add the suffix “X “to the old (existing) product’s part number. Your cooperation to this tentative identification method would be appreciated. After the fab transfer is completed, all the product part numbers will turn back to their original part numbers.





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List of affected parts:

ATP102-TL-H	ECH8308-TL-H
ATP104-TL-H	ECH8310-TL-H
ATP106-TL-H	ECH8410-TL-H
ATP108-TL-H	ECH8601M-TL-H
ATP114-TL-H	ECH8649-TL-H
ATP202-TL-H	ECH8651R-TL-H
ATP203-TL-H	ECH8652-TL-H
ATP204-TL-H	ECH8654-TL-H
ATP206-TL-H	ECH8655R-TL-H
ATP207-TL-H	ECH8659-M-TL-H
ATP208-TL-H	ECH8660-TL-H
ATP212-TL-H	ECH8662-TL-H
ATP213-TL-H	ECH8663R-TL-H
ATP301-TL-H	ECH8667-TL-H
ATP302-TL-H	ECH8673-TL-H
ATP404-TL-H	EMH2604-TL-H
ATP405-TL-H	MCH3377-TL-E
CPH3348-TL-E	MCH3475-TL-E
CPH6341-TL-E	MCH6336-TL-E
CPH6350-TL-E	SFT1350-TL-H
CPH6442-TL-E	MCH6337-TL-E